

Declaration of Compliance

DIRECTIVE 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast)

| Regulatory Model | Product Name |
|------------------|---------------------------------|
| NXS2U4NL12G500* | Converged Server/Storage System |

* NXS2U4NL12G500 Series will cover SX-1X65-G5 models.

The above listed product or product family has been verified to be in compliance with the European Union Restriction of Hazardous Substances, Directive 2011/65/EU. This declaration is based in part on information provided to Nutanix by its suppliers. To the best of our knowledge, the above listed product do not contain lead (Pb), mercury (Hg), hexavalent chromium (Cr(VI)), polybrominated biphenyls (PBB) and/or polybrominated diphenyl ethers (PBDE) in excess of the 0.1 wt% limit or cadmium (Cd) greater than 0.01 wt% limit except where valid exemptions have been granted by the European Union. The following exemptions were used to achieve compliance:

- 6a. Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
- 6b. Lead as an alloying element in aluminium containing up to 0.4% lead by weight
- 6c. Copper alloy containing up to 4% lead by weight
- 7a. Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)
- 7c(i). Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
- 7c(ii). Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
- 7c (iv). Lead in PZT based dielectric ceramic materials for capacitors which are part of integrated circuits or discrete semiconductors
- 13a. Lead in white glasses used for optical applications
- 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages



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